

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1643 (w/BR1225)	Aug-96	9630 B2	DALLAS	DA083158	N/A	28 MODULE

STRESS/JOB NO.

READPOINT

(Sample Size/No. of Fails)

Hi Temp Storage 70°C, No Bias P-17998, P-18019	<u>0 Hr</u>	<u>336 Hr</u>	<u>1K Hr</u>	<u>Elect. Test</u>	<u>Cum %</u>
	90/0	20/0	20/0	20/0	0.0%

Temp Cycle 0°C to +70°C P-18020	<u>300 ~</u>	<u>1K ~</u>	<u>Elect. Test</u>	<u>Cum %</u>
	35/0	35/0	35/0	0.0%

Moisture Soak 60°C/90% RH P-18021	<u>288 Hr</u>	<u>960 Hr</u>	<u>Elect. Test</u>	<u>Cum %</u>
	35/0	35/0	35/0 F1	0.0%

Phys. Dimen. <u>P-17997</u>	Solderability <u>P-17996</u>
6/0	24/0

Failure Mode

F1: Inlkg Lo

Failure Analysis

Device passed retest